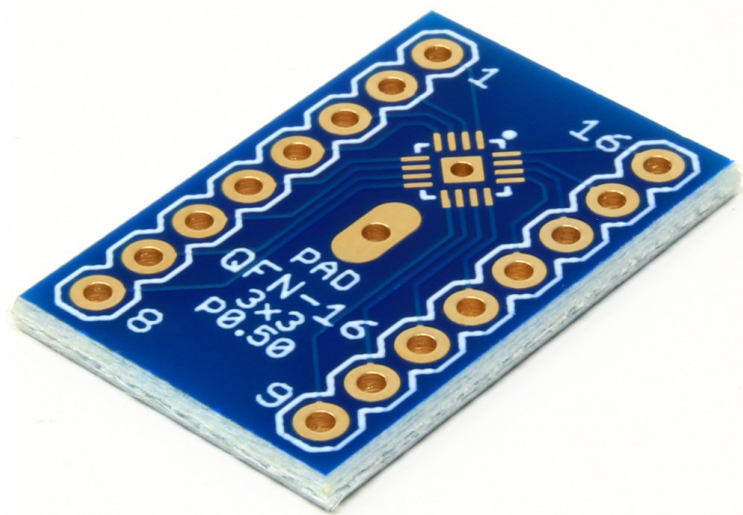


DA-QFN16-3X3P50

QFN-16 TO DIP ADAPTER – 3mm x 3mm – P0.50



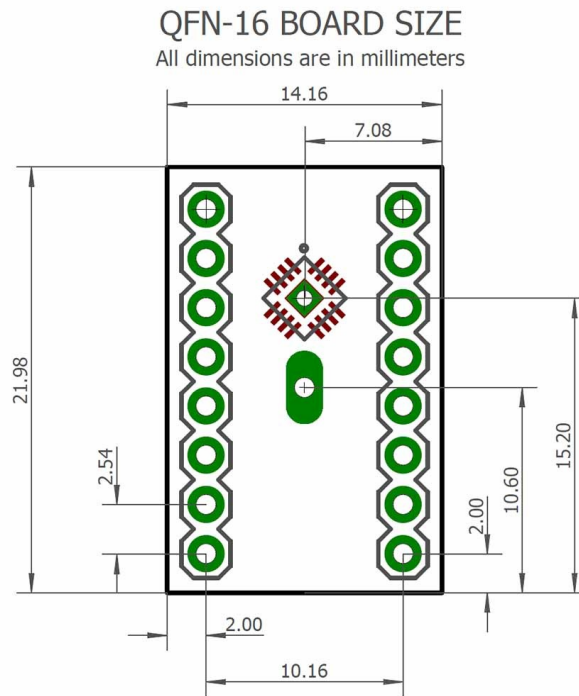
This adapter breaks out the pins of a QFN-16 component (with a body of 3mm x 3mm and 0.50mm pin pitch) into a board with 0.1" (2.54mm) spaced pins.

This is a high quality PCB, with all the copper pads and contacts plated with Electroless Nickel Immersion Gold (ENIG) process, offering an excellent surface planarity and oxidation resistance.

The land pattern includes a central pad that can be used to dissipate heat from a high-power integrated circuit, like a motor controller or an audio amplifier. There is also a hole drilled through the central pad that can be used to drop some solder and ensure dissipation and conductivity up to the component. The central pad is connected to a dedicated outer pad allowing to eventually wire a connection to it.

Specifications	
Supported packages	QFN-16
Package body size	3mm x 3mm
Component pin pitch	0.50mm
Board pin pitch	2.54mm (0.1")
Temperature rating	-25°C to +125°C
Material	FR4
RoHS compliant	Yes

Board dimensions



Land pattern dimensions

